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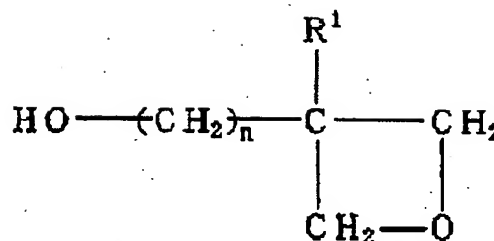
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TITLE : RESIN COMPOSITION FOR OPTICAL
MOLDING



ABSTRACT : PROBLEM TO BE SOLVED: To obtain the subject composition having high curing sensitivity with active energy light and capable of producing moldings in good productivity in shortened active energy light irradiation times by adding an oxetane monoalcohol to a specific resin composition for optical moldings.

SOLUTION: This resin composition comprises (A) a cationically polymerizable organic compound, (B) a radical-polymerizable organic compound, (C) an active energy light-sensitive cation polymerization initiator, (D) an active energy light-sensitive radical polymerization initiator, and (E) an oxetane monoalcohol, preferably at least one of compounds of the formula [R¹ is an alkyl, an aryl or an aralkyl; (n) is 1-6]. The component E is preferably contained in an amount of 1-30 wt.% based on the weight of the component A, and the component A preferably comprises at least one of epoxy compounds.

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